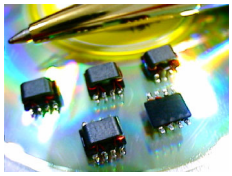


Product Series Code	**GTXF-002**	Brand	GOTREND
File Version	GTXF-002-V2	Editor	Robert
Established Date	1999.08.12	Description	Common Mode Filter for USB2.0 / IEEE1394
Latest Edit Date	2004.11.28	Pages	Page : 2

Features & Application:

* Common Mode Filter for USB2.0 / IEEE1394
* Fit for power line & signal line circuit
* To help you go pass the CE/FCC standard.
* Mobil Device / Handheld Device / LowProfile Device / Panel...

Part No Example:

GTXF - 002 - P - 5 - 900 - T

1 2 3 4 5 6

1. GTXF : GOTREND Seires
2. 002 : BALUN CORE with 8 Pin Base
3. P : Pb free <1000ppm
4. 5 : Height 5 mm Max
5. 900 : Impedance [ohm] @ 100MHz = 90 ohm
6. T : GOTREND internal code

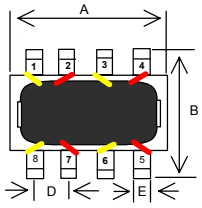
Product Structure

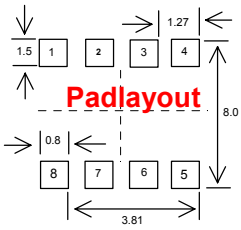
SMD	DIP	Shield	Unshield
			

2005 RoHS Compliant - SGS Certified Result

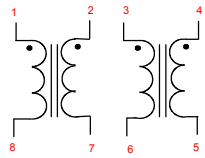
鉛 Pb	鎘 Cd	汞 Hg	六價鉻 Cr+6	溴化聯苯 PBB	溴化聯苯醚 PBDE
<1000ppm	ND	ND	ND	ND	ND

DIMENSION: [mm]





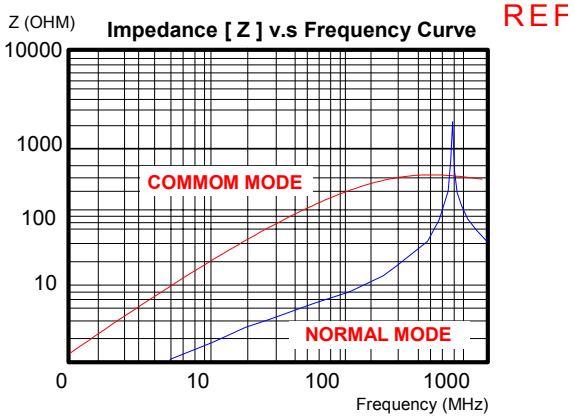
SCHEMATICS :



YELLOW WIRE RED WIRE

A=6.0 max, B=6.5 max , C=5.0 max, D=1.27+/-0.2, E=0.5+/-0.1

REF



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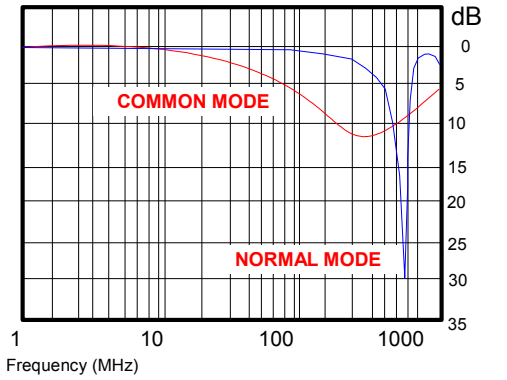


Test Equipment :

* HP4291A-Z, HP42841A- L,IDC,Q.RDC
* HP8753D NETWORK ANALYZER- SRF

Standard Atmospheric Conditions:
Ambient Temp:20+/-15°C
Relative Humidity:65+/-20%
If there may be any doubt on the result,
measurement shall be made within the following limits:
Ambient Temp:25+/-5°C
Relative Humidity:75+/-10%

Operatiing & Storage Condition:

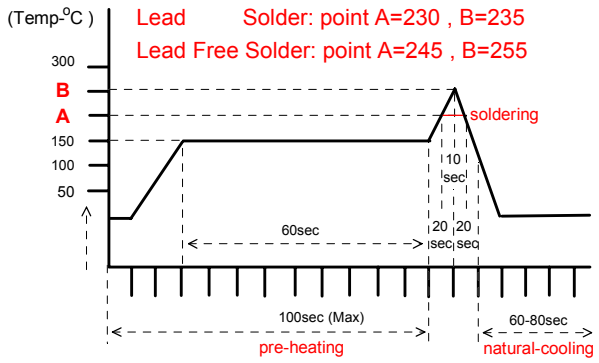
OPERATING TEMP:-40~+85°C

STORAGE TEMP:-40~+85°C
STORAGE LIFE TIME: 12 MONTH @25°C , RH 65%

Attention & Caution:

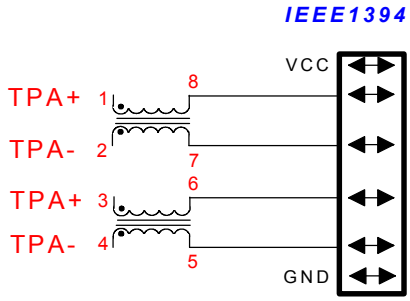
Please avoid following matters:
* Splashing water or salt water
* Toxic Gas (Hydrogen sulfide, Sulfurous acid, Chlorine, Ammonia)
* Vibrations or shocks which exced the specified condition
* Dew condenses
* Please be careful for the stress to this product by board flexure or something after the mounting.

Recommand Reflow Curve (TIME:Second)

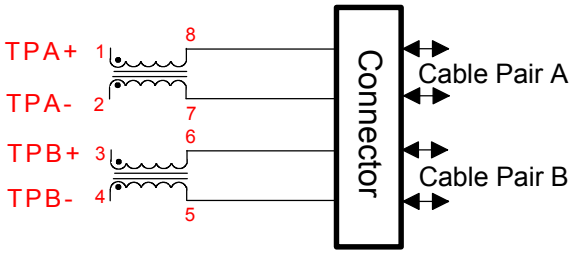


Notice: Iron Soldering: 3 Seconds Max. @260° C

IEEE1394 Application Circuit....



Twisted Pair Cable Application Circuit....



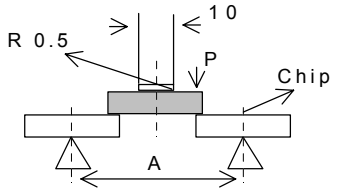
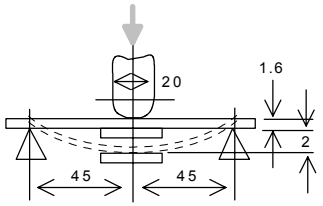
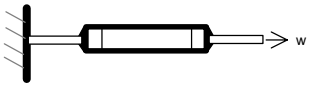
GTXF-002-5-XXXT Impedance Value

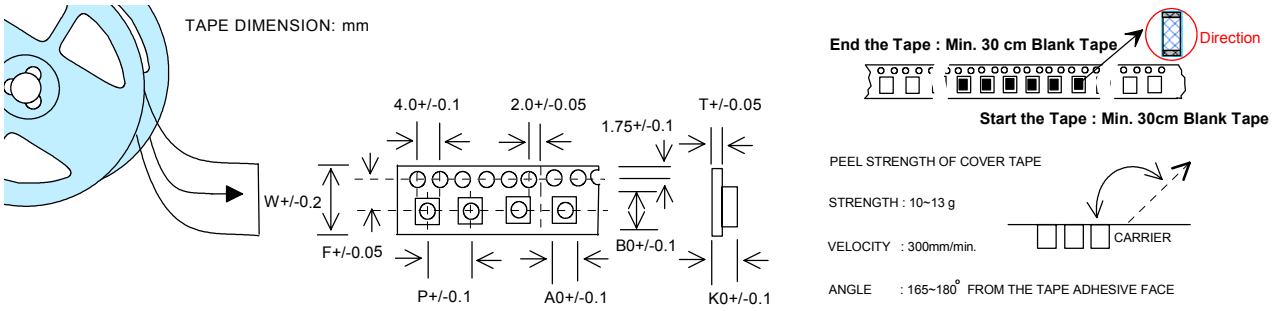
Part No.	Common Mode impedance(ohm) @50MHz(Min.)	Common Mode impedance(ohm) @100MHz(Min.)	Common Mode impedance(ohm) @300MHz(Min.)	Common Mode impedance(ohm) @500MHz(Min.)
GTXF - 002 - 5 - 900T	62	90	300	500
GTXF - 002 - 5 - 151T	112	150	400	600
GTXF - 002 - 5 - 261T	185	260	500	600
GTXF - 002 - 5 - 351T	250	350	600	680
GTXF - 002 - 5 - 461T	350	500	700	800

GTXF-002-5-XXXT Insertion Loss Value

Part No.	Common Mode Insertion Loss (dB)@50MHz	Common Mode Insertion Loss (dB)@100MHz	Common Mode InsertionLoss (dB)@300MHz	Common Mode InsertionLoss (dB)@500MHz	RDC (m ohm) (max)	IDC (max) (Amp)
GTXF - 002 - 5 - 900T	2.8+/-2.0	7.3+/-2.5	12.0+/-3.0	14.0+/-3.0	60	0.6
GTXF - 002 - 5 - 151T	2.8+/-2.0	7.3+/-2.5	12.0+/-3.0	14.0+/-3.0	70	0.5
GTXF - 002 - 5 - 261T	2.8+/-2.0	7.3+/-2.5	12.0+/-3.0	14.0+/-3.0	80	0.4
GTXF - 002 - 5 - 351T	2.8+/-2.0	7.3+/-2.5	12.0+/-3.0	14.0+/-3.0	90	0.3
GTXF - 002 - 5 - 461T	2.8+/-2.0	7.3+/-2.5	12.0+/-3.0	14.0+/-3.0	100	0.2

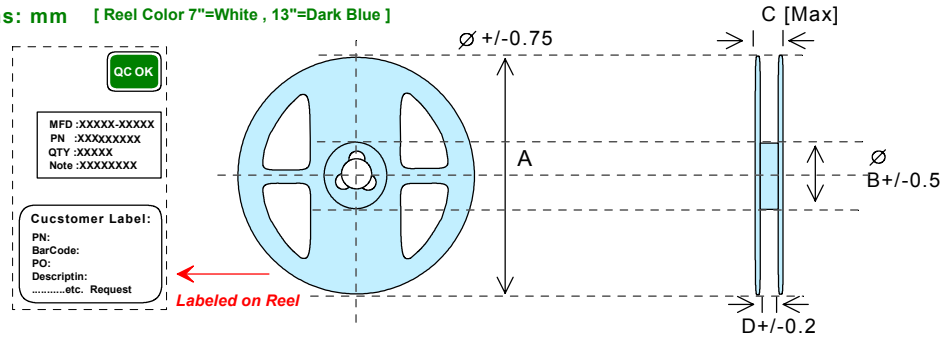
Reliability Test Result :

NO	ITEM	TEST CONDITIONS	REMARKS
1	Thermal Shock (Temperature Cycle) 溫度循環試驗	Temperature:-40 ° C/ +85 ° C kept stabilized for 30 minutes each Cycle: 100 Cycles	Inductance value shall be within ± 10% of the initial value. Q-factor shall be within ± 30% of the initial value. Impedance shall be within ± 20% of the initial value. DCR value shall be within ± 20% of the initial value.
2	Humidity Resistance 耐濕試驗	Humidity: 90%~ 95% RH Temperature: 40± 2 ° C Test Time: 1000± 12 Hours	■NO.1~4 Measurement:After placing for 24 hours (min.)
3	HighTemperature 耐熱試驗	Temperature: 85± 2 ° C Humidity: 20% Testing Time: 1000± 12 Hours	■NO.2~3 Applied current(spec): Rated current(maximum value)
4	Low Temperature 耐寒試驗	Temperature: -40 ± 2 ° C Time: 1000± 12 Hours	
5	Temperature and Humidity Cycle 溫/濕度循環試驗	Step / Temp / Humidity / Time 1 / 25± 2 ° C / 95~100%RH / 3.0Hr 2 / 55± 2 ° C / 95~96%RH / 9.5Hr 3 / 25± 2 ° C / 95~100%RH / 9.5Hr	■NO.5 Cycle: 5 cycles
6	Vibration 振動性試驗	Frequency: 10Hz~55Hz Amplitude: 1.5mm Direction: X,Y,Z Time: 2 Hours each	
7	IR Reflow Soldering 焊錫性試驗	Solder: H63A(eutectic solder) Solder Temp.: 230± 5 ° C Time: 6 minutes Cycles: x 1	Impedance(inductance) shall be within ± 20% of the initial value. DCR value shall be within ± 20% of the initial value.
8	Soldering Heat Resistance 耐熱 焊性試驗	Preheat:120 ~ 150 ° C (60 sec) Solder:H63A(eutectic solder) Solder Temp.: 260 ± 5 ° C Flux: Rosin Dip time: 10± 1 seconds	The chip must have no cracks.More than 75% of the terminal electrode must be covered with solder.
9	Bending Strength 折斷力試驗		The terminal electrode and the ferrite must not be damaged by the forces applied on the test conditions. ≧ 3 kg
10	Flexure Strength 彎曲試驗		No mechanical damage shall be noticed even when the board is bent 2 mm
11	Terminal Strength 拉力試驗		The terminal electrode and the ferrite must not be damaged by the forces applied on the test conditions. ≧ 2.0kg



SIZE/mm	A	B	C	D	E	F	G	H	I	J
GTXF	9.00	7.00	7.00	1.75	2.00	4.00	13.00	6.00	6.00	0.20

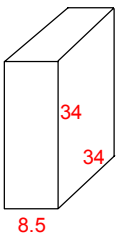
Reel Dimensions: mm [Reel Color 7"=White , 13"=Dark Blue]



SIZE / mm	A	B	C	D	REEL SIZE	QTY/REEL
GTXF	330	105	17	13	13”	1.5K

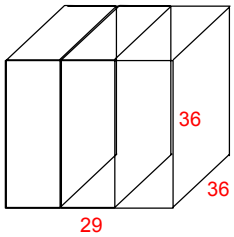
BOX Package: Unit: cm

4 Reel in



Inner Small Box

3 Inner Small Box in



Outter Large Box